

Kulicke & Soffa Receives Market Acceptance of Its Advanced Packaging Local Reflow Solution

SINGAPORE--(BUSINESS WIRE)-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company"), a global leader in the design and manufacture of semiconductor and LED assembly equipment, announced today that it has received its first purchase order for its APAMA™ (Advanced Packaging with Adaptive Machine Analytics) Advanced Packaging solution from a strategic, technology focused customer. The APAMA series is a single platform solution for Thermo-Compression (TC), High-Density Fan-Out Wafer-Level-Packaging and High-Accuracy Flip Chip applications.

"This purchase order is an important milestone in our Advanced Packaging platform initiative," Tong Liang Cheam, Kulicke & Soffa's Vice President of the Advanced Packaging Business Line and Corporate Strategy stated. "Designed for performance and accuracy, the K&S APAMA platform is positioned to enable the next generation of fine-pitch devices at the best cost of ownership."

Introduced in 2014, the APAMA Series provides compelling throughput, placement accuracy, metrology, and overall cost-of-ownership advantages for the emerging Advanced Packaging market. Demand for enhanced performance, reduced form-factor and improved power efficiency, combined with challenges relating to die shrink are collectively driving the growth of the Advanced Packaging market. As the industry moves to adopt innovative packaging techniques, exciting new and meaningful growth opportunities are emerging for K&S.

Patrick Desjardins, Director of the Advanced Packaging Local Reflow Business Line stated, "Along with this first purchase order we continue to be deeply engaged with key customers as market interest for our Advanced Packaging solutions expands. The ability to address multiple application variants, coupled with a wide range of metrology capabilities adds meaningful production value and further differentiates our APAMA solution from the competition."

K&S has also successfully qualified the APAMA TC Bonder at a large strategic customer and is preparing to deploy 10 additional APAMA TC Bonders for demo and evaluation purposes to customers in Taiwan, Korea, China, Singapore and United States over the coming months. The Company continues to demonstrate the APAMA capabilities through its active customer sampling program. K&S application labs in Korea, Singapore, Taiwan and the United States are facilitating this program and are engaged with several leading customers.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a global leader in the design and manufacture of semiconductor, LED and electronic assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, advanced SMT, wedge bonding and a broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation

semiconductor and LED devices. (www.kns.com)

Caution Concerning Results and Forward Looking Statements

In addition to historical statements, this press release contains statements relating to future events and our future results. These statements are "forward-looking" statements within the meaning of the Private Securities Litigation Reform Act of 1995, and include, but are not limited to, statements that relate to our future revenue, sustained, increasing, continuing or strengthening demand for our products, the continuing transition from gold to copper wire bonding, replacement demand, our research and development efforts, our ability to identify and realize new growth opportunities and our ability to control costs. While these forward-looking statements represent our judgments and future expectations concerning our business, a number of risks, uncertainties and other important factors could cause actual developments and results to differ materially from our expectations. These factors include, but are not limited to: the risk that customer orders already received may be postponed or canceled, generally without charges; the risk that anticipated customer orders may not materialize; the risk that our suppliers may not be able to meet our demands on a timely basis; the volatility in the demand for semiconductors and our products and services; a substantial completion of transition from gold to copper wire bonding by the industry, volatile global economic conditions, which could result in, among other things, sharply lower demand for products containing semiconductors and for the Company's products, and disruption of capital and credit markets; the risk of failure to successfully manage our operations; acts of terrorism and violence; risks, such as changes in trade regulations, currency fluctuations, political instability and war, which may be associated with a substantial non-U.S. customer and supplier base and substantial non-U.S. manufacturing operations; and the factors listed or discussed in Kulicke and Soffa Industries, Inc. 2015 Annual Report on Form 10-K and our other filings with the Securities and Exchange Commission. Kulicke and Soffa Industries, Inc. is under no obligation to (and expressly disclaims any obligation to) update or alter its forward-looking statements whether as a result of new information, future events or otherwise.

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